

DIP AOI

S-AX520 series

Double-sided
automatic optical
inspection machine



Double-sided automatic optical inspection machine



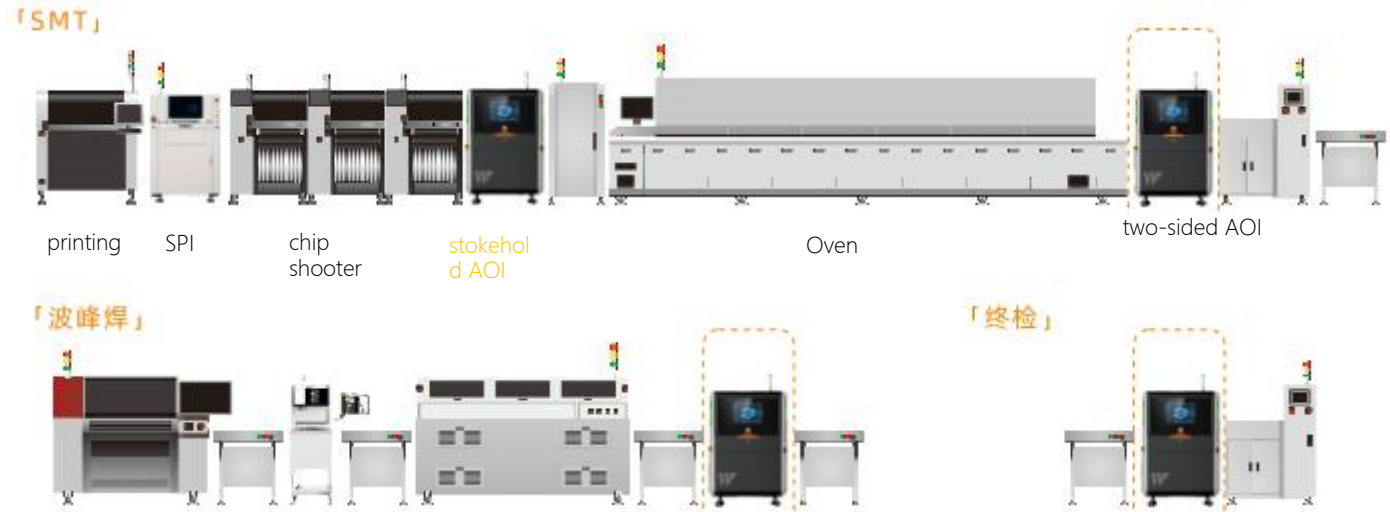
S-A X 520 series has completed the one-stop unmanned final inspection scheme for PCBA products, which is widely used for peak-back and double-sided final inspection.

"Product Features"

- Above and below detection at the same time, one machine to complete the detection of two machines, simplify the process, save plant space
- Dual camera synchronous position, asynchronous interlocking image, to avoid the interference of the upper and lower light sources
- Optional wheel plate mode, more high temperature resistance, dirty, heavy load, meet the peak process requirements
- Plate positioning, FOV positioning with feature point algorithm, welding joint inspection ability is strong
- CPU stitching special algorithm, accurate spread catch stitching bending, deformation and lack of needle and other defects.



"One machine is versatile"



Plug-in machine, large field AOI, peak furnace double-sided AOI double-sided AOI

"Detection instance"



▲ Good ▲ direction ▲ good ▲ deviation ▲ good ▲ missing ▲ tin hole ▲ no foot ▲ tin ▲ missing needle

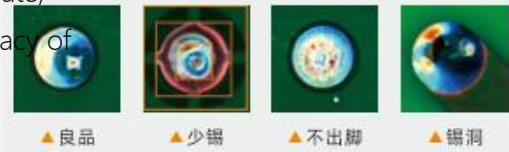
Technological superiority

- Component level pad positioning + FOV auxiliary positioning technology

○ For the flexible plate, using the element level welding plate positioning, effectively solve the false report and missing report caused by the strange deformation of the plate;



○ Adopt FOV overall positioning for the nonflexible plate, which can ignore the interference of screen printing and printing line on the plate, and can easily realize the welding pad positioning, ensure the accuracy of detection,



- DIP solder joint special algorithm

○ Equipped with hand-plug and machine plug-in DIP solder joint detection special algorithm.

"Features"

- centralized management

The centralized management of AOI in the production line can realize remote recovery, offline programming and debugging update.

- Scan the code automatic line change

By identifying the PCB bar code to automatically widen and call the program, without manual participation, and support MES instruction implementation.

- Double-sided bar code binding

Double panel process, only one side of the bar code, can be from Dynamic-binding double-panel test results.

- Major adverse stay prevention

Effectively prevent key components and key adverse outflow.

- SPC early warning

Real-time monitoring of production line production quality, timely feedback of abnormal conditions, to prevent batch bad outflow.

- output whole plot

At the end of the test, the whole panel circular image is output, including the component area and no component area, to meet the later quality traceability requirements.

"Parameter Specification"

Model equipment		S-AX520	S-AX520XL
Image system	camera	5MP / 20MP industrial camera	
	Divide change rate	5MP camera: 24 μ m, 15 μ m; 12MP camera: 15um	
	FOV	60*49mm(5MP, 24um)60*45mm(12MP, 15um)	
	camera lens	Far heart lens	
	illuminant	4-color ring-programmed LED Light Source (RGBW)	
Far moving institutions	X/Y movement	AC servo	AC servo-dual-drive
	Orbit broadening mode	self-correcting	
	Track type	Belt (standard), optional wheel	
	Into the plate flow	Left to right or right to left (pre-factory setting)	
	Fixed track	Before the rail	
Hardware configuration	operating system	Win10	
	communication mode	Ethernet , SMEMA	
	source	Monophphase 220V, 50 / 60Hz, 5A	
	pressure	0.4-0.6Mpa	
	orbit altitude	900 + 20mm (standard standard), 740 + 20mm is optional	
	weight	900kg	
	Machine size	L1170 * D1608 * H1580mm (excluding lamp)	customizable
Check the PCB specifications	size	50*50-510*510mm	50*50-650*610mm
	Board heavy	10kg (optional wheel: 30kg)	
	temperature resistance	60°C (optional wheel: 150°C)	
	thickness	0.6-6mm (optional wheel: 6.0mm)	
	clear height	The upper net height is 25-85mm adjustable, and the lower net height is 25-80mm adjustable	
	plate edges	3.0mm	
Inspection item	Component class	Wrong parts, missing parts, polarity, deviation, flip, damage, IC bending foot, foreign body, monument, etc	
	Welding tin class	Lack of needles, tin run, Wuxi, less / more tin, no foot, virtual welding, dew copper, tin ball, even tin, etc	
	Check the components	Chip: 03015 and above: LSI: 0.3mm spacing and above; other: alien elements	
	Detection speed	200-250ms/FOV	

"Equipment Dimensions"

